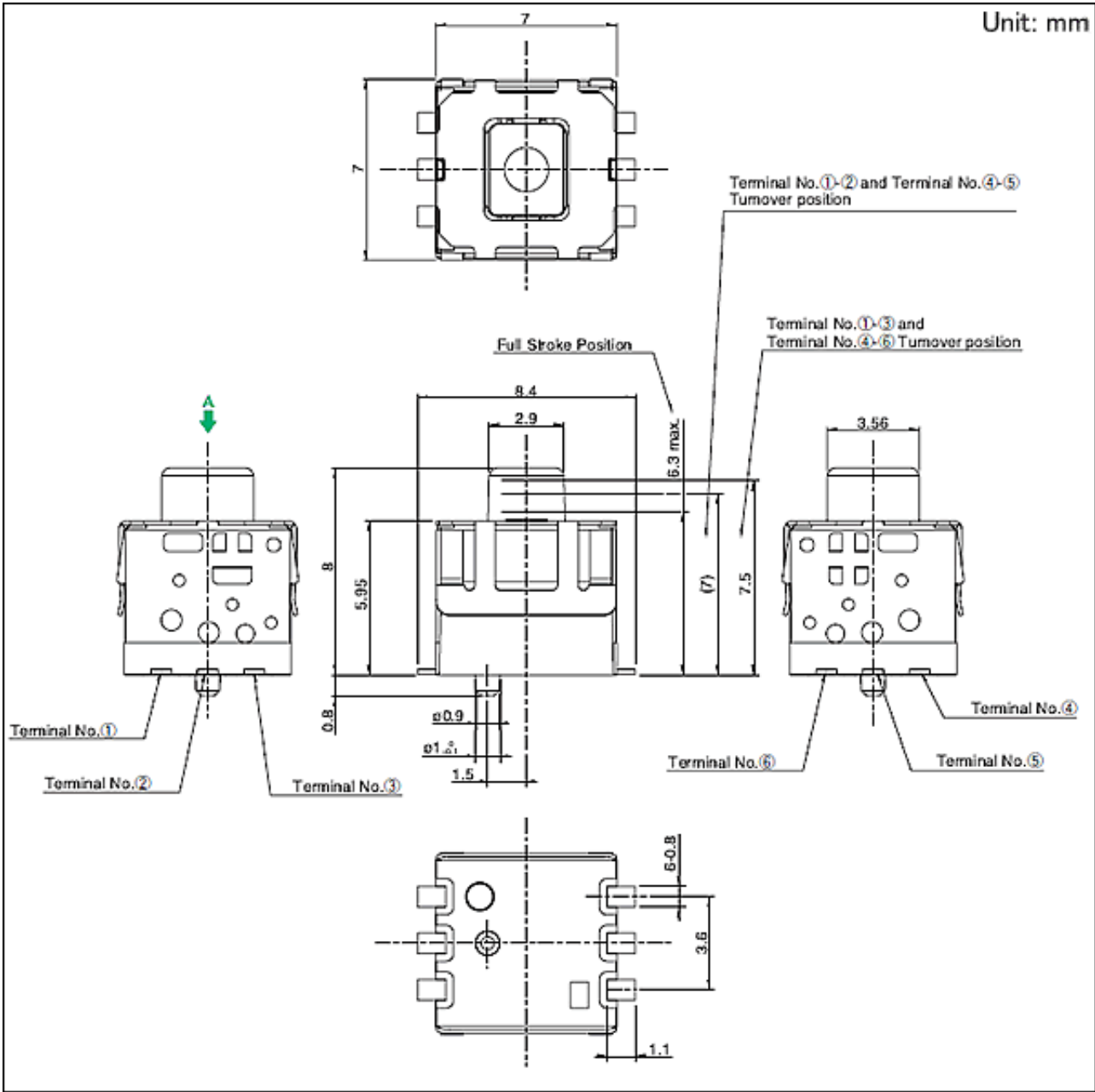


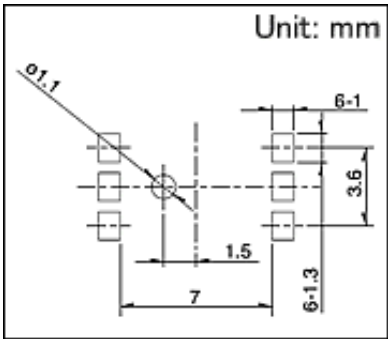
Compact Momentary Type SPEJ Series

Part number		SPEJ110100
Travel		1.7mm
Operating force		3.5±0.7N
Poles		2
Positions		2
Operating temperature range		-40℃ to +85℃
Electrical performance	Contact resistance (Initial performance/After lifetime)	150mΩ max./150mΩ max.
	Insulation resistance	100MΩ min. 500V DC
	Voltage proof	500V AC for 1 minute
Mechanical performance	Actuator strength Operating direction	49N
Rating (max.)(Resistive load)		0.2A 14V DC
Durability	Operating life without load	10,000 cycles 150mΩ max.
	Operating life with load (at max. rated load)	10,000 cycles 150mΩ max.
Environmental performance	Cold	-40±2℃ for 500h
	Dry heat	85±2℃ for 500h
	Damp heat	60±2℃, 90 to 95%RH for 500h
Minimum order unit (pcs.)	Japan	500
	Export	2,000

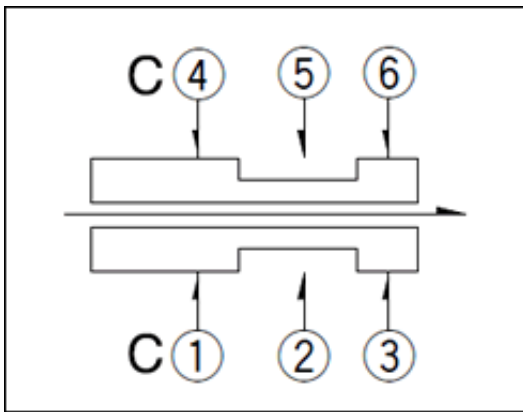
Dimensions



Recommend Pattern

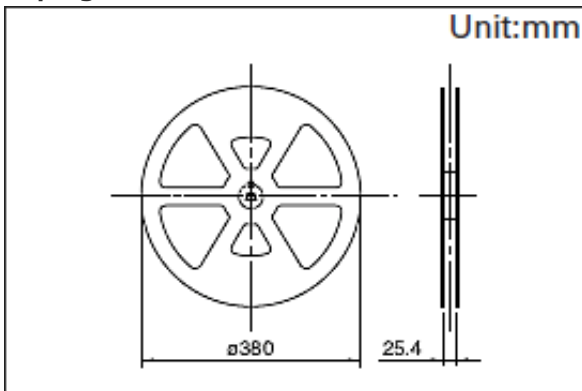


Circuit Diagram



Packing Specifications

Taping



Number of packages 1 reel (pcs.)	500
1 case / Japan	1,000
1 case / export packing	2,000
Tape width (mm)	24
Export package measurements (mm)	404×397×140

Soldering Conditions

Example of Reflow Soldering Condition

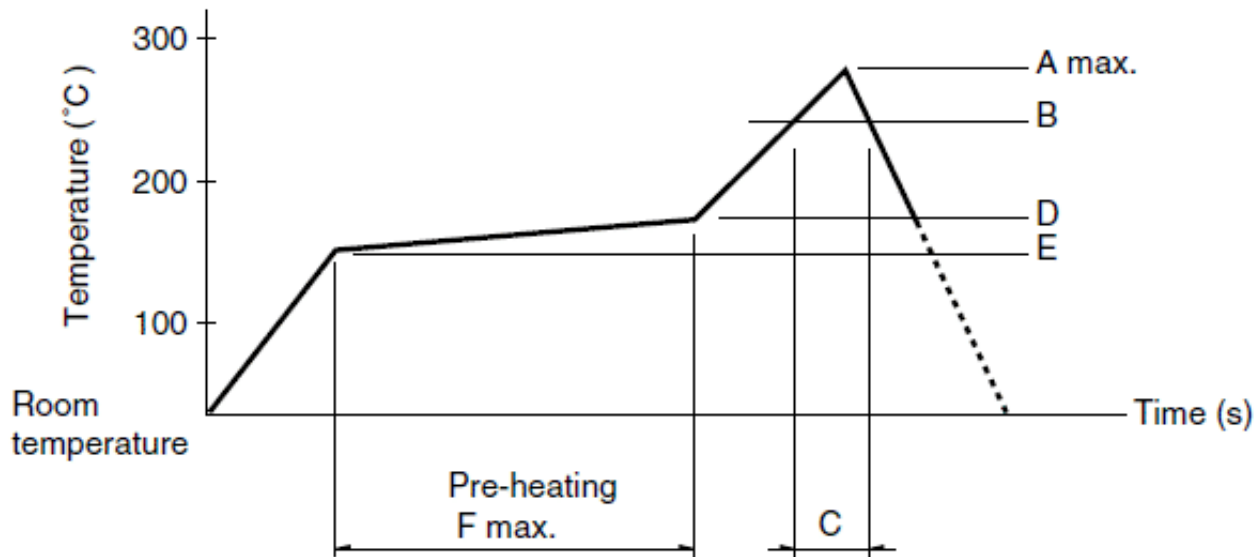
1. Heating method

Double heating method with infrared heater.

2. Temperature measurement

Thermocouple 0.1 to 0.2 Φ CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile



A(°C) 3s max.	B(°C)	C(s)	D(°C)	E(°C)	F(s)
260	230	40	180	150	120

(1) The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.

(2) Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Soldering temperature	350±5°C
Soldering time	4s max.